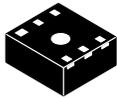# MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS
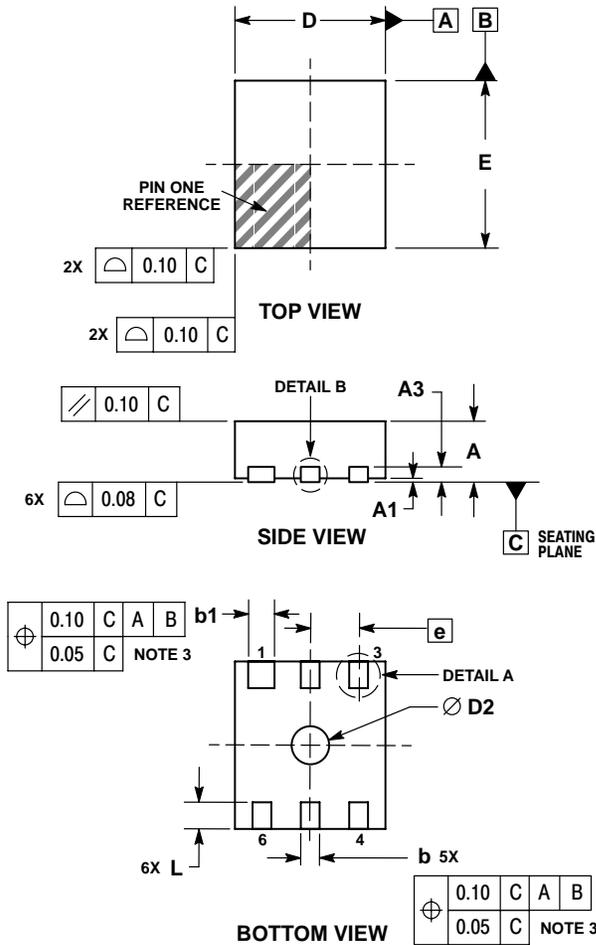
ON Semiconductor®

DFN6 2x2.2 mm
CASE 488–03
ISSUE G

DATE 06 FEB 2006

SCALE 4:1

PIN ONE REFERENCE

2X ⌒ 0.10 C

TOP VIEW

2X ⌒ 0.10 C

∥ 0.10 C

DETAIL B

6X ⌒ 0.08 C

SIDE VIEW

C **SEATING PLANE**

⊕ 0.10 C A B
0.05 C **NOTE 3**

DETAIL A

∅ **D2**

6X **L**

b 5X

BOTTOM VIEW

⊕ 0.10 C A B
0.05 C **NOTE 3**

EDGE OF PACKAGE

L1

DETAIL A
Bottom View
(Optional)

MOLD CMPD **EXPOSED Cu**

A1

DETAIL B
Side View
(Optional)

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. TERMINAL b MAY HAVE MOLD COMPOUND MATERIAL ALONG SIDE EDGE.
6. DETAILS A AND B SHOW OPTIONAL VIEWS FOR END OF TERMINAL LEAD AT EDGE OF PACKAGE AND SIDE EDGE OF PACKAGE.

| DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3	0.20 REF		
b	0.20	0.25	0.30
b1	0.30	0.35	0.40
D	2.00 BSC		
D2	0.40	0.50	0.60
E	2.20 BSC		
e	0.65 BSC		
L	0.30	0.35	0.40
L1	0.00	0.05	0.10

GENERIC MARKING DIAGRAM*

xxM

xx = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.

SOLDERING FOOTPRINT*

$\frac{0.50}{0.020}$

$\frac{0.65}{0.025}$

$\frac{0.40}{0.016}$

$\frac{0.50}{0.020}$

$\frac{1.9}{0.075}$

$\frac{0.65}{0.025}$
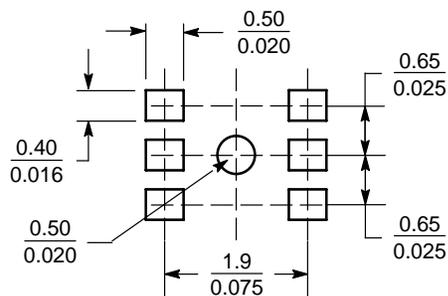
SCALE 10:1

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**DFN6 2 X 2.2 X 0.9 X 0.65P**	**PAGE 1 OF 2**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY J. HOSKINS.	30 JAN 2001
A	REMOVED DIM'S E,F,K,M,N,P,Q AND R. UPDATED VIEW. REQ. BY M. JONES.	23 MAY 2001
B	REMOVED IDENT PIN. SWAPPED THE TOP LEFT AND RIGHT PAD LOCATIONS. REQ. BY M. SALEH.	13 SEP 2001
C	CHANGED DESCRIPTION FROM 2 X 2 TO 2 X 2.2. CHANGE MARKING DIAGRAM. REQ. BY K. OPPEN.	27 JUN 2003
D	CHANGED MARKING DIAGRAM. REQ. BY S. RIGGS.	30 JUL 2003
E	ADDED "U' DIMENSION TO DIMENSION TABLE. REQ. BY K. OPPEN.	03 MAR 2004
F	CHANGED DEVICE DESCRIPTION FROM QFN TO DFN. REQ. BY A. GARLINGTON.	02 NOV 2005
G	CHANGED DRAWING FORMAT TO STANDARD FORMAT. REQ. BY B. LOFTS.	06 FEB 2006